PCN Number:		20210915000.1A				P	CN Date:	October 28, 2021	
Title:	Qualify additional Assembly sites for select SOT devices								
Custo	mer Contact:	<u>P(</u>	CN Manager	nager		Dept:	Quality Services		
Proposed 1 st Ship Date:		Dec 20, 2021		Estimated Sample Availability:		Provided upon Request			
Change Type:									
Assembly Site				Design			Wafer B	Wafer Bump Site	
Assembly Process				Data Sheet W		Wafer B	ump Material		
Assembly Materials				Part number change			Wafer B	Wafer Bump Process	
Mechanical Specification		tion		Test Site			Wafer F	Wafer Fab Site	
□ Packing/Shipping/Labeling			Test Process Wafer F		ab Materials				
								Wafer F	ab Process
PCN Details									

Description of Change:

Revision A is to announce the <u>addition</u> of new devices that was not included on the original PCN notification. The new devices are listed on the Product Affected section below. The expected first shipment date for the new device will be 90 days from this notice (Jan. 27, 2022) for the newly added device only. The proposed 1st ship date of Dec 20, 2021 still applies for the original set of devices.

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:

SOT-23 (DBV)				
Assembly Sites	TIPI, ASEWH, HFTF, HNA, TFME, TIEM, CDAT			
Lead Finish	NiPdAu; NiPdAuAg; Matte Sn			
	400180			
	A-03			
Mount compound	4213245			
	400194			
	4207123			
	R-27			
	8097131			
	R-13			
Mold Compound	450413			
	R-04			
	450042			
	4222198			

Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>INA193AIDBVR</u> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. **INA193AIDBVRG4.**"

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

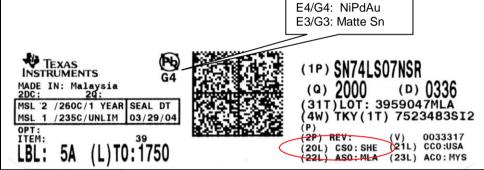
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
	No Change	No Change	$oxed{\boxtimes}$ No Change

Changes to product identification resulting from this PCN:

Assembly Site		
TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI
ASEWH	Assembly Site Origin (22L)	ASO: AWH
HFTF	Assembly Site Origin (22L)	ASO: HFT
HNA	Assembly Site Origin (22L)	ASO: HNT
TFME	Assembly Site Origin (22L)	ASO: NFM
TI Chengdu (CDAT)	Assembly Site Origin (22L)	ASO: CDA
TI Melaka (TIEM)	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)



Product Affected:

SN74LVC1G02DBVR	SN74LVC1G08DBVR	SN74LVC1G125DBVR
SN74LVC1G02DBVRG4	SN74LVC1G08DBVRG4	TLV9041UIDBVR

DBV (SOT-23) Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/- (Note a)
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74AHC1G14DBV	HNA INA293A1IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (SN74LVC1GU04DBV)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TIEMA DAC121S101CIMK	HFTAT TLV70333DBV	ASEWH TL431CDBV
TC	Temperature Cycling -65/150C	500 Cycles	-	3/231/0	3/231/0
TC	Temperature Cycling -55/150C	1000 Cycles	3/231/0	-	-
HAST	Biased HAST 130C/85%RH	96 hours	-	3/231/0	3/231/0
THB	Temperature Humidity Bias 85C/85%RH	1000 hours	3/231/0	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM2660MM/NOPB)	3/66/0 (TLV74333PDBV)	3/66/0
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collection in progress. Data will be made available upon request after completion.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

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